# Advanced Deep Space System Development Program

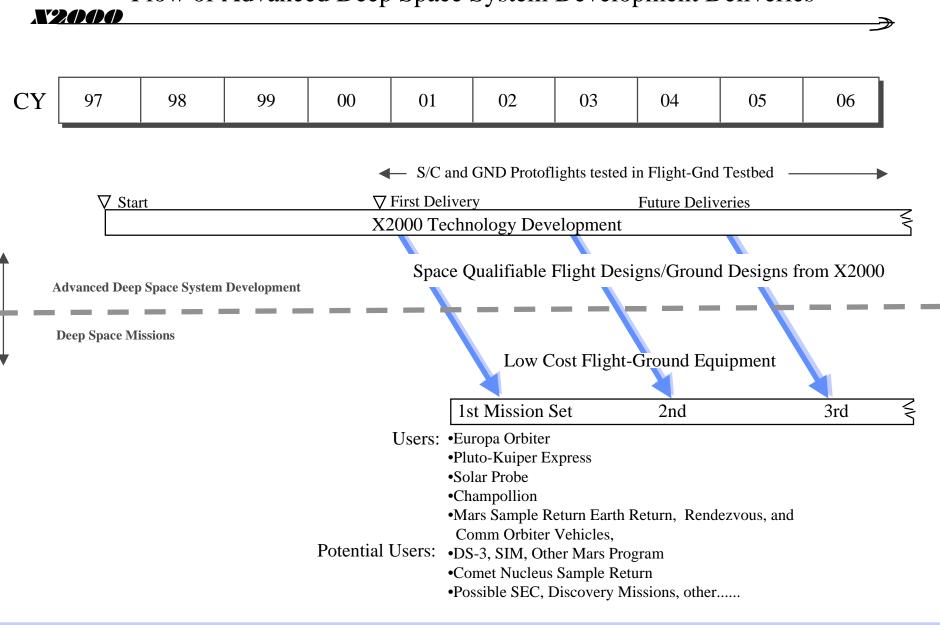
# FIRST DELIVERY

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### Flow of Advanced Deep Space System Development Deliveries



### Advanced Deep Space System Development 1st Delivery

### X2000



### AN INTEGRATED and QUALIFIED engineering model FLIGHT and GROUND SYSTEM

- Flight System Micro-electronics
  - Computer and memory
    - Neural Network
    - Digital Signal Processor
  - Power & Pyro Switching
  - Sensor/Instrument I/O
  - Scaleable, modular, long life
  - RAD Hardened Designs and Parts
  - Low Temperature, low power
  - X and Ka Band Comm
  - Optical Comm -- Possible
- F/S and GND S/W with W.S:
  - Operating systems
  - Generic auto NAV, 3-Axis A/C
  - Generic F/S-GND autonomy
  - Generic F/S-GND science data processing
  - Generic GND CMD/TLM processing/display
- ARPS power source
- Other: Micro-electronic components, structure, thermal, propulsion, etc. as budget allows

### Flight System Summary

An Example for a Europa Orbiter





- Radar sounder, LIDAR, mult. spec. WAC & MAC

o Telecom

- Redundant Optical Com/NAC/Laser Alt receiver

- Single DSTT with X-band SSPA & MGA

o Data System

- 3D Stack MCM Computers (3)

- Stacked memory Solid State Recorder

- Multiple buses/variable power draw

o Power

- 150 W. ARPS

- Power & pyro switching microelectronics

o Attitude Control

- 3 axis stabilized

- Adv. Stellar Compass w/CPU

- Solid state IMU

- Sun sensors

o Propulsion

- 400 N dual mode w/liquid regulators

- 20 N TVC biprop thrusters

- Monoprop 1 N and 5 mN RCS thrusters

o Temperature Control

- ARPS waste heat

- MLI blankets and louvers

- RHU's

- Electric heaters

### **Performance**

Pointing Control 2 mrad
Pointing Knowledge 1.5 mrad
Rate Control <10 µrad/sec
Processor Speed 4-50 MHz
Data Bus Rate 50 Mb/sec

Data Storage Redundant 16 Gb

Downlink (Optical) ~100 Kb/sec @Europa

Power 150 W @Europa

 $\Delta V$  Capability 2.5 km/sec

Legend:

MCM - Multichip Module

MAC/NAC/WAC - Medium/Narrow/Wide Angle Camera

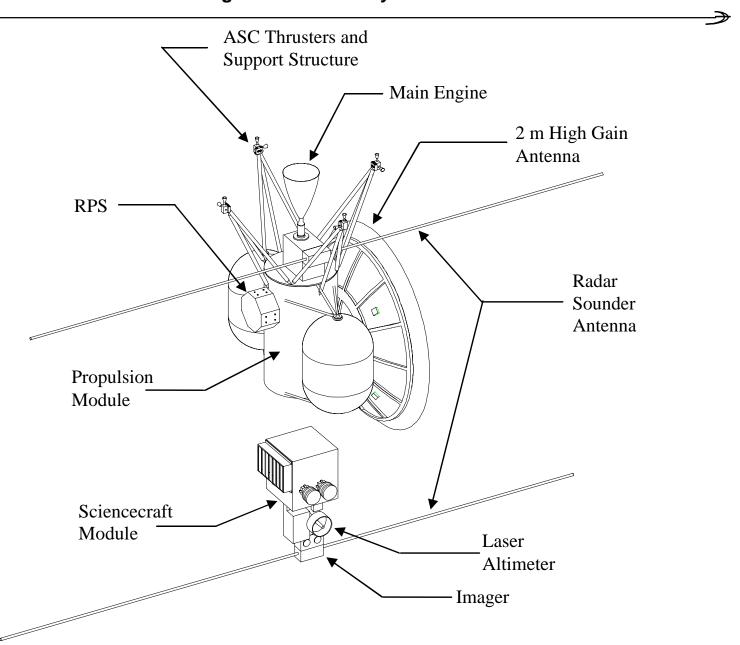
DSTT - Tiny Deep Space Transponder

ARPS - Advanced Radioisotope Power Source MLI - Multi-layer insulation

RCS - Reaction Control System
IMU - Inertial Measurement Unit

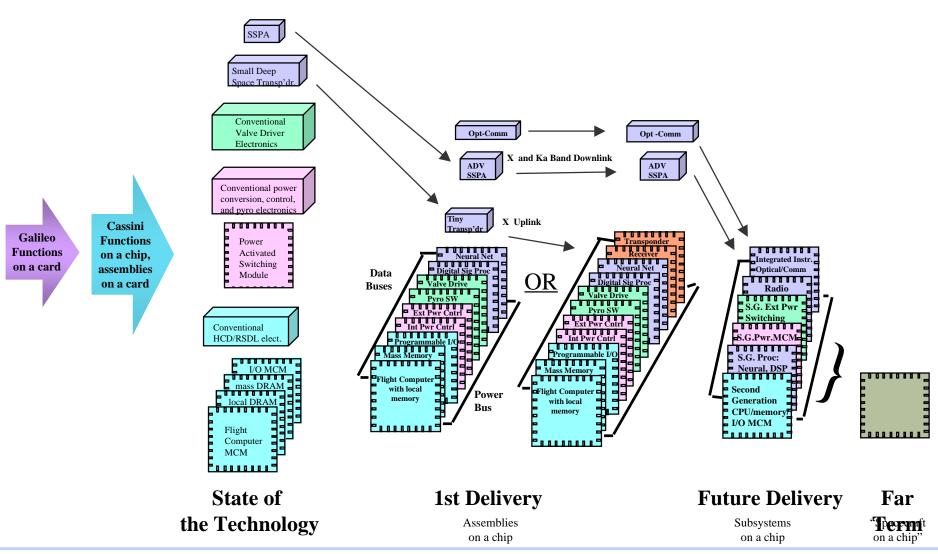
RHU - Radioisotope Heater Unit

# Europa Orbiter Configuration using an RF telecom system



### Advanced Deep Space System Development

### X2000



**HCD/RSDL** = Hardware Command Decoder/Need Solar Downlink **PWR** = Power

MCM = Multi-chip Modes OPT = Optical SSPA = Solid State Power Amplifier

NMP = New Millennium Program DS1= Deep Space 1, 1st NMP Technology Demo Flight

## Technology Development and Insertion

### X2000

- Microelectronics
  - 3D MCM Stacking
  - Integrates C&DH, Attitude Control, Telecom, and Power & Pyro Switching
  - Multifunctional Structure
  - HDI power electronics
  - Provides a general purpose scaleable processing environment, inc:
    - Digital Signal Processors
    - Multi-processor architecture
    - Neural Nets
- Advanced Radioisotope Power Source
- Software
  - Unified flight and ground system architecture, employing flight and ground autonomy, tasks readily transfered between ground and flight
  - On-board, distributed applications and processing
  - On-board planning of flight system activities and navigation
  - Software Implemented Fault Tolerance
  - Scaleable to mission needs; a general platform for mission to build upon

# Technology Development and Insertion

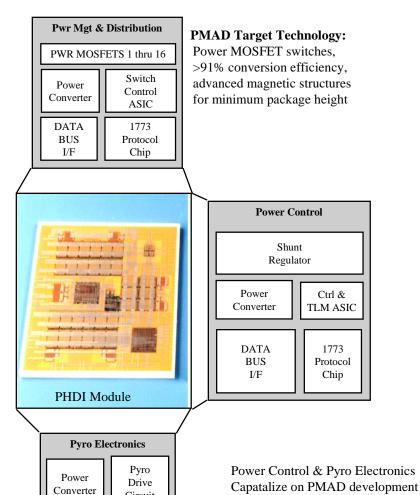
### X2000

- RF telecom
  - Transponder integrated with avionics
- Optical Communications
  - Comm Terminal capable of >100 kbps from Europa orbit
    - Also acts as laser altimeter receiver
    - Also acts as extremely high-resolution science imager
- Altitude control
  - Advanced Stellar Compass
- Propulsion
  - Hydrazine µthrusters
  - Variable liquid regulators
- Parts & Materials
  - Low voltage/power, rad hard electronic parts ( $\leq 3.3$ V for digital electronics)
  - Electronics parts list with radiation dose tolerances selectable by missions
  - Unshielded materials capable of withstanding radiation dose >25 Mrad
- Additional options
  - Next generation SEP
  - Optical processing

### Power Microelectronics Technologies

#### X2000





Circuit

1773

Protocol

Chip

DATA

BUS

I/F

#### Overview

Current Technology: PC Board packaging, discrete component control circuit, relay enable and command switches and SCR fire circuit for pyros

**Target Technologies:** 1. Mixed signal ASICs, 2. Power High Density Interconnect (PHDI) packaging, 3. modular fault tolerant design

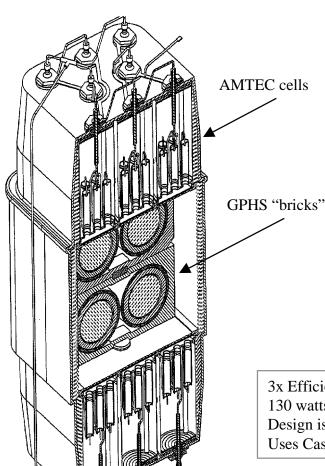
Benefits: 1. Reduce mass and volume, 2. standard command interface, 3. Provides peak power at maximum load, 4. configurable to various power source characteristics

Impact of Fallback: Several kg mass increase, increase in volume

**Key Issues:** Laser vs. NSI Pyro technology, thermal design, fault tolerant control circuit

# Advanced Radioisotope Power Source (ARPS) Technology





#### **Overview**

**Current Technology:** *Galileo/Cassini* heritage RTG with 6-7% efficiency

unicouple conversion

**Target Technology:** >20% conversion using either AMTEC

Benefits: Mass reduction, smaller quantity of radioisotope

**Key Issues:** lifetime; efficiency; radiator size; heat rejection temperature

**Impact of Fallback:** > 12 kg mass increase

3x Efficiency over RTG's 130 watts after 15 yrs Design is scaleable in 50W Units Uses Cassini GPHS

# Optical Communications Technology

### X2000



**Current Technology:** X/Ka-band RF telecommunications systems

**Target Technology:** 30-cm optical comm terminal, uplink & downlink

**Benefits:** Dramatic increase in telemetry rate at mass and power levels equivalent to RF telecom system; see plot below

Key Issues: lifetime, system-level fault protection

Impact of Fallback: Reduction in science data returned

